

Description

The HCSD18563Q5A uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =80 A

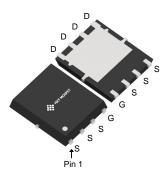
 $R_{DS(ON)} < 7m\Omega$ @ $V_{GS}=10V$

Application

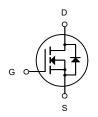
Battery protection

Load switch

Uninterruptible power supply



DFN5X6-8L DFN-8(5.1x5.7))



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
HCSD18563Q5A	DFN5X6-8L(DFN-8(5.1x57))	HXY MOSFET	5000

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	V		
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	А		
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	А		
Ідм	Pulsed Drain Current ²	rent ² 320		
EAS	Single Pulse Avalanche Energy ³	169	mJ	
P _D @T _C =25°C	Total Power Dissipation ⁴	108	W	
Тѕтс	Storage Temperature Range	ture Range -55 to 150		
TJ	Operating Junction Temperature Range	ge -55 to 150		
Rejc	Thermal Resistance Junction-Case ¹		°C/W	



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic				l	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Charac	cteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	3	4	V
R _{DS(on)}	Static Drain-Source on-Resistance	V _{GS} =10V, I _D = 30A	-	5.3	7	mΩ
Dynamic C	Characteristics					
C _{iss}	Input Capacitance	.,	-	4136	-	pF
Coss	Output Capacitance	V _{DS} =30V, V _{GS} =0V,	-	286	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	257	-	pF
Qg	Total Gate Charge	.,	-	90	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =30V, I _D =30A,	-	9	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	V _{GS} =10V	-	18	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		_	9	-	ns
t _r	Turn-on Rise Time	V _{DS} =30V, I _D =30A,	-	7	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =1.8Ω, V _{GS} =10V	-	40	-	ns
t _f	Turn-off Fall Time		-	15	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	А
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	320	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F =30A, dl/dt=100A/μs	-	46	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition : TJ=25 $^{\circ}\mathrm{C}$, VDD=30V, VG=10V, L=0.5mH, Rg=25 Ω , IAS=26A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

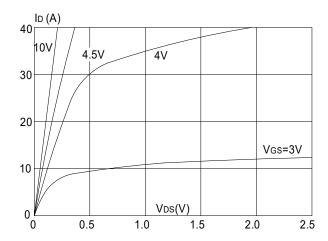


Figure 3:On-resistance vs. Drain Current

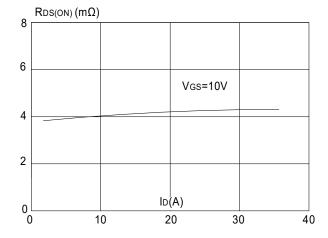


Figure 5: Gate Charge Characteristics

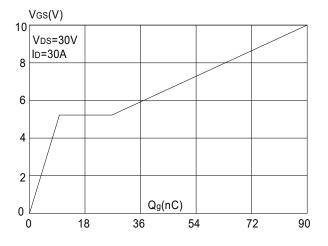


Figure 2: Typical Transfer Characteristics

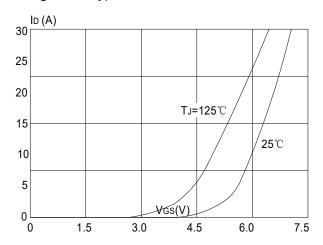


Figure 4: Body Diode Characteristics

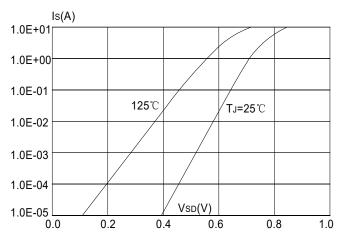


Figure 6: Capacitance Characteristics

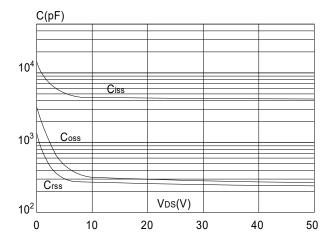




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

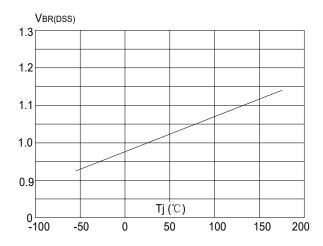


Figure 9: Maximum Safe Operating Area

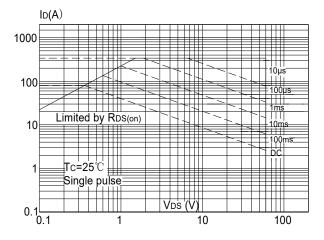


Figure.11: Maximum Effective
Transient Thermal Impedance, Junction-to-Case
ZthJ-c(℃/W)

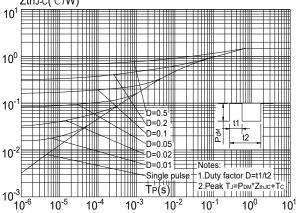


Figure 8: Normalized on Resistance vs. Junction Temperature

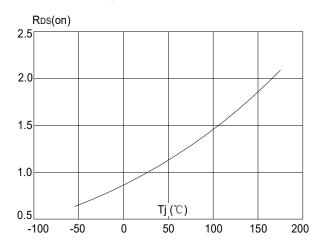
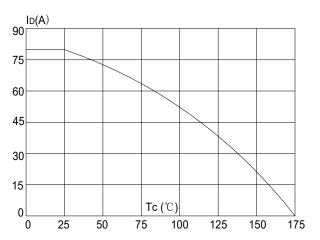
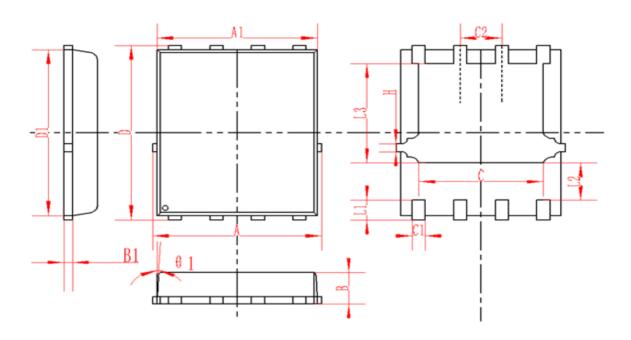


Figure 10: Maximum Continuous Drain Current vs. Case Temperature





DFN5X6-8L(DFN-8(5.1x5.7))Package Information



SYMBOL	MM		INCH			
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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